- Member of the Texas Instruments Widebus™ Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

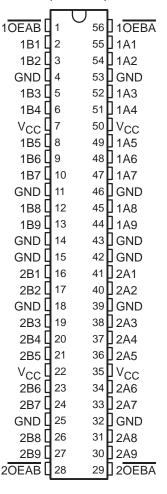
### description

This 18-bit bus transceiver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH16863 is an 18-bit noninverting transceiver designed for synchronous communication between data buses. The control-function implementation minimizes external timing requirements.

The SN74ALVCH16863 can be used as two 9-bit transceivers or one 18-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the output-enable (OEAB or OEBA) inputs.

#### DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16863 is characterized for operation from -40°C to 85°C.

# FUNCTION TABLE (each 9-bit section)

INP	UTS	ODEDATION
OEAB	OEBA	OPERATION
Н	L	B data to A bus
L	Н	A data to B bus
Н	Н	Isolation

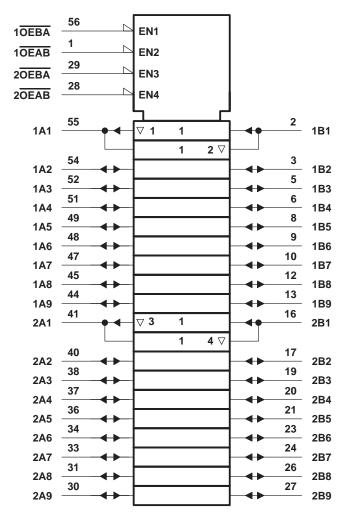


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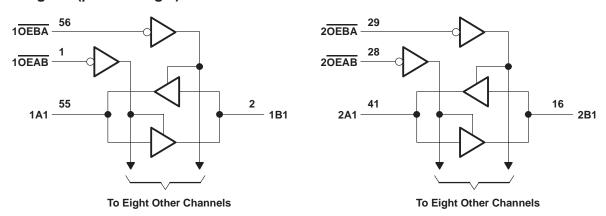


### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)





SCES060B - DECEMBER 1995 - REVISED FEBRUARY 1999

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, I <sub>O</sub>	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG pac	kage 81°C/W
	ge 74°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		1.65	3.6	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
٧ı	Input voltage		0	VCC	V
٧o	Output voltage		0	Vcc	V
		V <sub>CC</sub> = 1.65 V		-4	
1	High level output gurrent	V <sub>CC</sub> = 2.3 V		-12	mA
ЮН	High-level output current	V <sub>CC</sub> = 2.7 V		-12	IIIA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 1.65 V		4	
1	Lave laved autout average	V <sub>CC</sub> = 2.3 V		12	
IOL	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
		V <sub>CC</sub> = 3 V		24	1
Δt/Δν	Input transition rise or fall rate	·		10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST Co	ONDITIONS	Vcc	MIN	TYP <sup>†</sup>	MAX	UNIT
		I <sub>OH</sub> = -100 μA		1.65 V to 3.6 V	V <sub>CC</sub> -0.	.2		
		I <sub>OH</sub> = -4 mA		1.65 V	1.2			
		I <sub>OH</sub> = -6 mA		2.3 V	2			
Vон				2.3 V	1.7			V
		I <sub>OH</sub> = -12 mA		2.7 V	2.2			
				3 V	2.4			
		I <sub>OH</sub> = -24 mA		3 V	2			
		I <sub>OL</sub> = 100 μA		1.65 V to 3.6 V			0.2	
		I <sub>OL</sub> = 4 mA		1.65 V			0.45	
		I <sub>OL</sub> = 6 mA		2.3 V			0.4	V
VOL		10 1		2.3 V			0.7	V
		I <sub>OL</sub> = 12 mA		2.7 V			0.4	
		I <sub>OL</sub> = 24 mA		3 V			0.55	
lį		V <sub>I</sub> = V <sub>CC</sub> or GND		3.6 V			±5	μΑ
		V <sub>I</sub> = 0.58 V		1.65 V	25			
		V <sub>I</sub> = 1.07 V		1.65 V	-25			
		V <sub>I</sub> = 0.7 V		2.3 V	45			
I <sub>I</sub> (hold)		V <sub>I</sub> = 1.7 V		2.3 V	-45			μΑ
		V <sub>I</sub> = 0.8 V		3 V	75			
		V <sub>I</sub> = 2 V		3 V	-75			
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$		3.6 V			±500	
loz		$V_O = V_{CC}$ or GND		3.6 V		-	±10	μΑ
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ
ΔlCC		One input at V <sub>CC</sub> – 0.6 V,	Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V			750	μΑ
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND		3.3 V		3.5		pF
Co	Data inputs Outputs	$V_O = V_{CC}$ or GND		3.3 V		7.5		pF

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> =		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> =		UNIT
	(INFO1)	(001F01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> pd	A or B	B or A	§	1	4.1		4	1	3.4	ns
t <sub>en</sub>	OEAB or OEBA	A or B	§	1	5.7		5.8	1	4.7	ns
<sup>t</sup> dis	OEAB or OEBA	A or B	§	1.3	5.5		4.7	1.4	4.2	ns

<sup>§</sup> This information was not available at the time of publication.



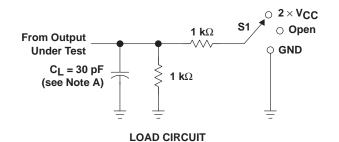
<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

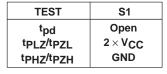
### operating characteristics, T<sub>A</sub> = 25°C

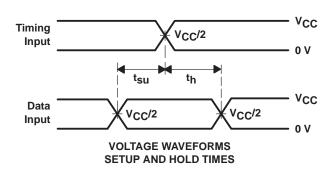
	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
	FARAMETER		TEST CONDITIONS	TYP	TYP	TYP	ONIT
	Power dissipation	Outputs enabled	C <sub>1</sub> = 50 pF, f = 10 MHz	†	21	30	pF
C <sub>pd</sub>	capacitance	Outputs disabled		†	2	3	þг

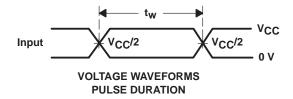
<sup>†</sup> This information was not available at the time of publication.

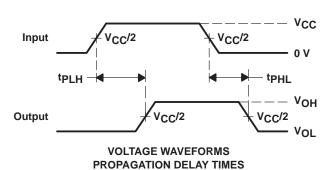
# PARAMETER MEASUREMENT INFORMATION V<sub>CC</sub> = 1.8 V

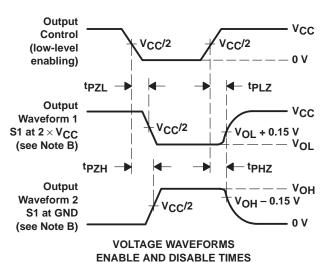












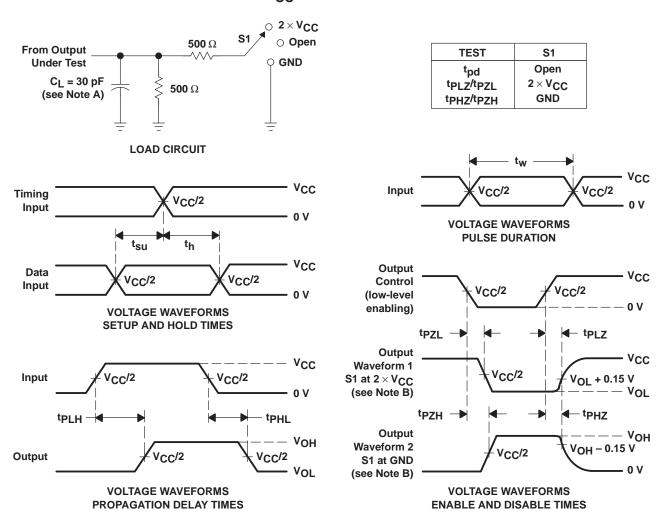
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2 ns.  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



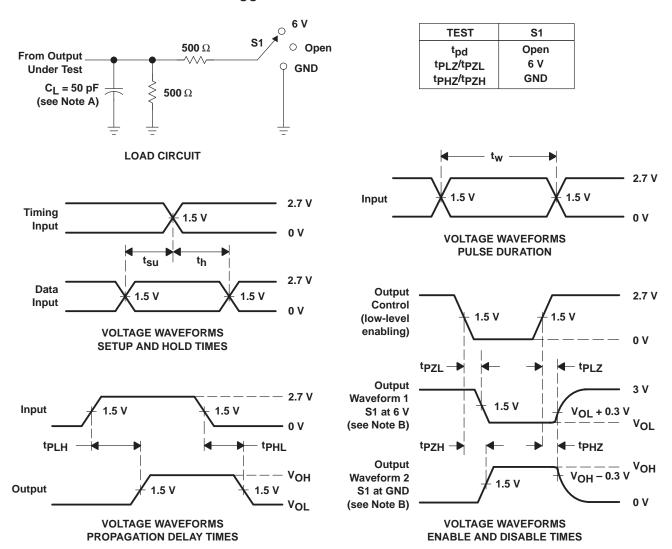
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2$  ns.  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



### PACKAGE OPTION ADDENDUM

10-Dec-2020

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74ALVCH16863DGGR	ACTIVE	TSSOP	DGG	56	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16863	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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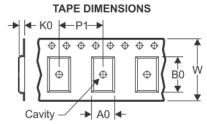
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# PACKAGE MATERIALS INFORMATION

www.ti.com 24-Aug-2017

### TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
ı		Dimension designed to accommodate the component length
I	K0	Dimension designed to accommodate the component thickness
ı	W	Overall width of the carrier tape
-	P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16863DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

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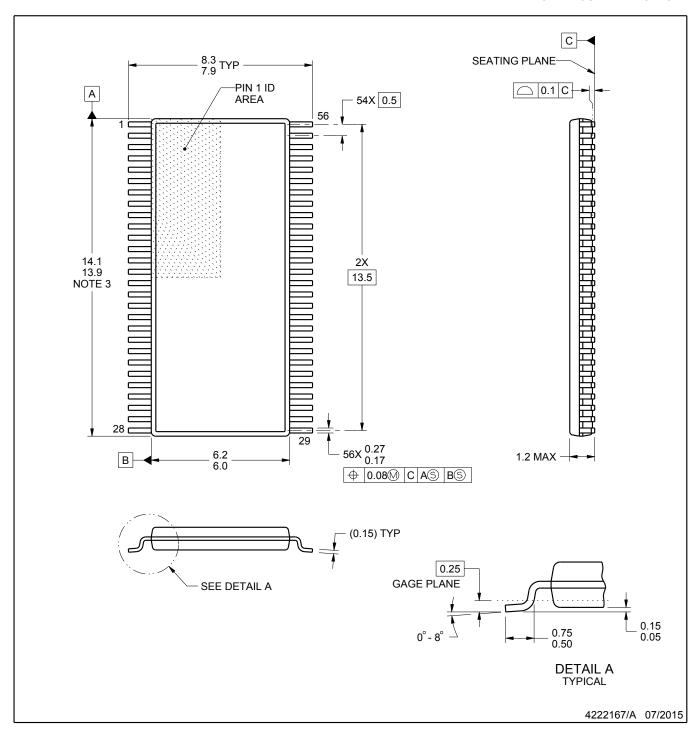


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16863DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0



SMALL OUTLINE PACKAGE



### NOTES:

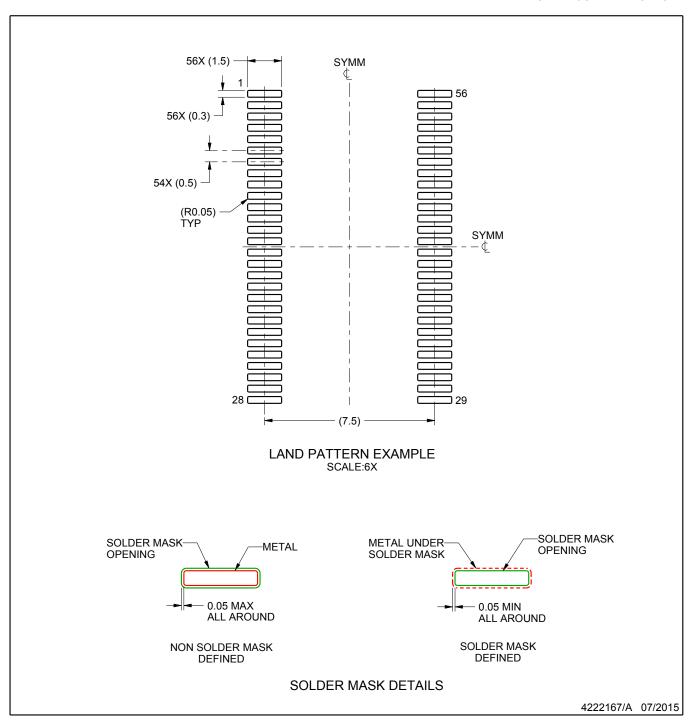
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

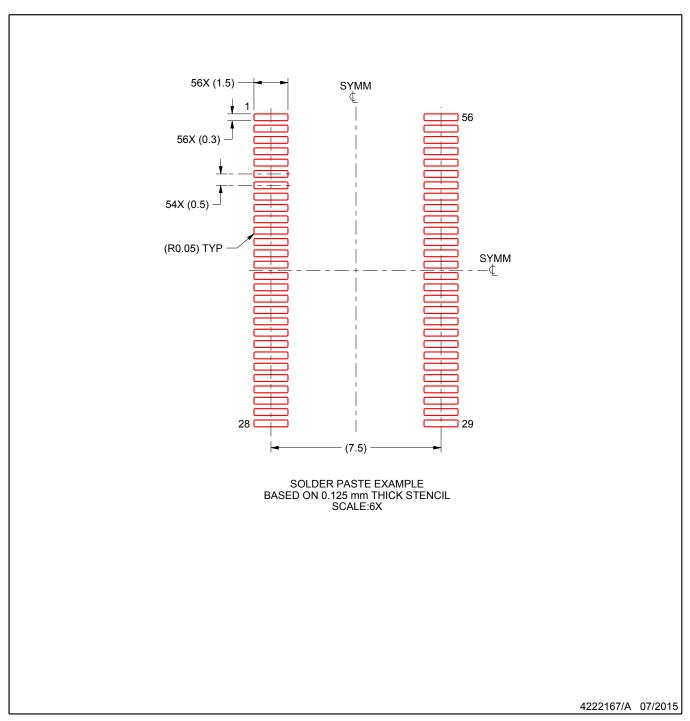


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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